



Material Composition Declaration

EPC2302

Company Name	Efficient Power Conversion (EPC)	Issue Date:	10/19/2022
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	31.2 mg	Type of Product:	eGaN FET in FCQFN package

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	9.8134	31.4101	33.3767	314101
	Silicon oxide	7631-86-9	0.0912	0.2919		2919
	Silicon nitride	12033-89-5	0.0306	0.0981		981
	Gallium nitride	25617-97-4	0.0659	0.2111		2111
	Aluminum	7429-90-5	0.1317	0.4216		4216
	Aluminum nitride	24304-00-5	0.0140	0.0448		448
	Titanium	7440-32-6	0.0026	0.0084		84
	Titanium nitride	25583-20-4	0.1258	0.4026		4026
	Copper	7440-50-8	0.0022	0.0070		70
	Tungsten	7440-33-7	0.0095	0.0303		303
	Polyimide		0.1408	0.4508		4508
Under Bump Metal	Titanium	7440-32-6	0.0010	0.0031	0.0340	31
	Copper	7440-50-8	0.0097	0.0309		309
Solder Bump	Copper	7440-50-8	0.8115	2.5973	3.5490	25973
	Nickel	7440-02-0	0.0576	0.1844		1844
	Tin	7440-31-5	0.2354	0.7533		7533
	Silver	7440-22-4	0.0043	0.0138		138
Package	Copper	7440-50-8	11.7262	37.5324	63.0404	375324
	Iron	7439-89-6	0.3007	0.9624		9624
	Mold Compound		7.0000	22.4051		224051
	Tin	7440-31-5	0.6688	2.1406		21406
Sum in total:			31.2430	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.